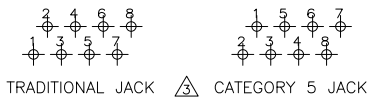
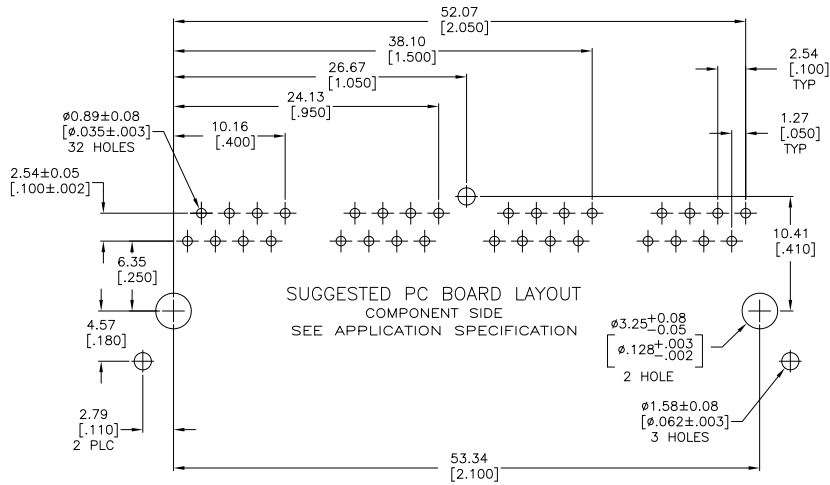
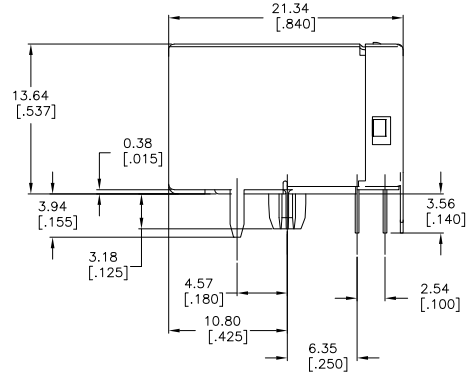
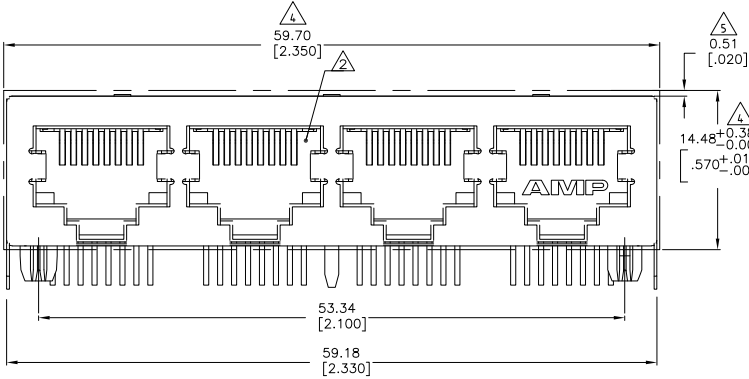


THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION. ALL RIGHTS RESERVED.

LOC	DIST	REVISIONS		
AA	00	F LTR	DESCRIPTION	DATE
		D	ECR-11-017936	28OCT2011 JJ MQW



- MATERIAL: HOUSING— HIGH TEMPERATURE NYLON, BLACK, IR COMPATIBLE, UL 94V-0.
TERMINALS - 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27um[.000050] MINIMUM HARD GOLD IN LOCALIZED AREA AND 3.81um[.000150] MINIMUM TIN IN SOLDER AREA OVER 1.27um[.000050] MINIMUM NICKEL UNDERPLATE
SHIELDS - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 1.27 um [.000050] MINIMUM NICKEL AND 2.03 um [.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
- △ JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
 - △ CAUTION: CATEGORY 5 JACK SOLDER TAIL POSITIONS DO NOT FOLLOW SAME NUMBER SEQUENCE AS THAT OF THE TRADITIONAL JACKS.
 - △ SUGGESTED PANEL OPENING DIMENSIONS
 - △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING

5558503-1
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DRN W. LONG/A. MAYER 04NOV2008	TE Connectivity
		CHK J. WESTMAN 04NOV2008	
DIMENSIONS: mm [INCHES]		APPRO. S. ELCKINGER 04NOV2008	MODULAR JACK ASSEMBLY, PORT, B POSITION, RIGHT ANGLE, CATEGORY 5E, PC BOARD GROUND SHIELD
TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC 108-1163-2	
0 PLG ± -	1 PLG ± -	APPLICATION SPEC 114-2048	SIZE CASE CODE DRAWING NO. A2 00779 C=5558503
2 PLG ± -	3 PLG ± -	FINISH -	RESTRICTED TO -
4 PLG ± -	ANGLES ± -	MATERIAL -	
SEE NOTE 1	SEE NOTE 1	CUSTOMER DRAWING	SCALE 4:1 SHEET 1 of 1 REV D